

# 74LVC1G14

## Single Schmitt-trigger inverter

Rev. 8 — 10 November 2010

Product data sheet

### 1. General description

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The 74LVC1G14 provides the inverting buffer function with Schmitt-trigger action.

The input can be driven from either 3.3 V or 5 V devices. This feature allows the use of this device in a mixed 3.3 V and 5 V environment. Schmitt-trigger action at the input makes the circuit tolerant for slower input rise and fall time.

This device is fully specified for partial power-down applications using  $I_{OFF}$ . The  $I_{OFF}$  circuitry disables the output, preventing the damaging backflow current through the device when it is powered down.

### 2. Features and benefits

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- Wide supply voltage range from 1.65 V to 5.5 V
- High noise immunity
- Complies with JEDEC standard:
  - ◆ JESD8-7 (1.65 V to 1.95 V)
  - ◆ JESD8-5 (2.3 V to 2.7 V)
  - ◆ JESD8-B/JESD36 (2.7 V to 3.6 V).
- $\pm 24$  mA output drive ( $V_{CC} = 3.0$  V)
- CMOS low power consumption
- Latch-up performance exceeds 250 mA
- Direct interface with TTL levels
- Unlimited rise and fall times
- Input accepts voltages up to 5 V
- Multiple package options
- ESD protection:
  - ◆ HBM JESD22-A114F exceeds 2000 V
  - ◆ MM JESD22-A115-A exceeds 200 V.
- Specified from  $-40$  °C to  $+85$  °C and  $-40$  °C to  $+125$  °C.

### 3. Applications

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- Wave and pulse shaper
- Astable multivibrator
- Monostable multivibrator



## 4. Ordering information

Table 1. Ordering information

Type number	Package			Version
	Temperature range	Name	Description	
74LVC1G14GW	-40 °C to +125 °C	TSSOP5	plastic thin shrink small outline package; 5 leads; body width 1.25 mm	SOT353-1
74LVC1G14GV	-40 °C to +125 °C	SC-74A	plastic surface-mounted package; 5 leads	SOT753
74LVC1G14GM	-40 °C to +125 °C	XSON6	plastic extremely thin small outline package; no leads; 6 terminals; body 1 × 1.45 × 0.5 mm	SOT886
74LVC1G14GF	-40 °C to +125 °C	XSON6	plastic extremely thin small outline package; no leads; 6 terminals; body 1 × 1 × 0.5 mm	SOT891
74LVC1G14GN	-40 °C to +125 °C	XSON6	extremely thin small outline package; no leads; 6 terminals; body 0.9 × 1.0 × 0.35 mm	SOT1115
74LVC1G14GS	-40 °C to +125 °C	XSON6	extremely thin small outline package; no leads; 6 terminals; body 1.0 × 1.0 × 0.35 mm	SOT1202

## 5. Marking

Table 2. Marking

Type number	Marking code <sup>[1]</sup>
74LVC1G14GW	VF
74LVC1G14GV	V14
74LVC1G14GM	VF
74LVC1G14GF	VF
74LVC1G14GN	VF
74LVC1G14GS	VF

[1] The pin 1 indicator is located on the lower left corner of the device, below the marking code.

## 6. Functional diagram

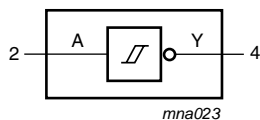


Fig 1. Logic symbol

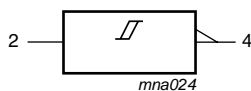


Fig 2. IEC logic symbol

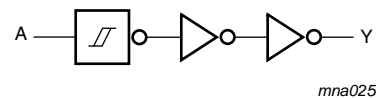
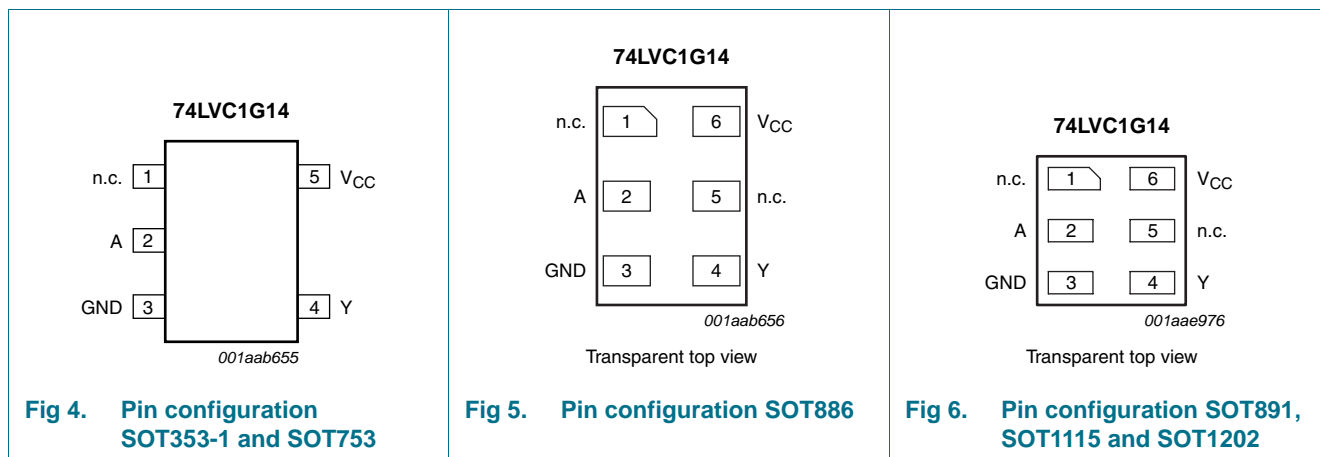


Fig 3. Logic diagram

## 7. Pinning information

### 7.1 Pinning



### 7.2 Pin description

Table 3. Pin description

Symbol	Pin		Description
	SOT353-1, SOT753	SOT886, SOT891, SOT1115, SOT1202	
n.c.	1	1	not connected
A	2	2	data input
GND	3	3	ground (0 V)
Y	4	4	data output
n.c.	-	5	not connected
V <sub>CC</sub>	5	6	supply voltage

## 8. Functional description

Table 4. Function table<sup>[1]</sup>

Input	Output
A	Y
L	H
H	L

[1] H = HIGH voltage level; L = LOW voltage level

## 9. Limiting values

**Table 5. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{CC}$	supply voltage		-0.5	+6.5	V
$V_I$	input voltage		[1] -0.5	+6.5	V
$V_O$	output voltage	Active mode	[1][2] -0.5	$V_{CC} + 0.5$	V
		Power-down mode	[1][2] -0.5	+6.5	V
$I_{IK}$	input clamping current	$V_I < 0$ V	-50	-	mA
$I_{OK}$	output clamping current	$V_O > V_{CC}$ or $V_O < 0$ V	-	$\pm 50$	mA
$I_O$	output current	$V_O = 0$ V to $V_{CC}$	-	$\pm 50$	mA
$I_{CC}$	supply current		-	+100	mA
$I_{GND}$	ground current		-100	-	mA
$T_{stg}$	storage temperature		-65	+150	°C
$P_{tot}$	total power dissipation	$T_{amb} = -40$ °C to +125 °C	[3] -	250	mW

[1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

[2] When  $V_{CC} = 0$  V (Power-down mode), the output voltage can be 5.5 V in normal operation.

[3] For TSSOP5 and SC-74A packages: above 87.5 °C the value of  $P_{tot}$  derates linearly with 4.0 mW/K.  
For XSON6 package: above 118 °C the value of  $P_{tot}$  derates linearly with 7.8 mW/K.

## 10. Recommended operating conditions

**Table 6. Recommended operating conditions**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{CC}$	supply voltage		1.65	-	5.5	V
$V_I$	input voltage		0	-	5.5	V
$V_O$	output voltage	Active mode	0	-	$V_{CC}$	V
		Power-down mode; $V_{CC} = 0$ V	0	-	5.5	V
$T_{amb}$	ambient temperature		-40	-	+125	°C

## 11. Static characteristics

**Table 7. Static characteristics**

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	-40 °C to +85 °C			-40 °C to +125 °C		Unit
			Min	Typ <sup>[1]</sup>	Max	Min	Max	
V <sub>OH</sub>	HIGH-level output voltage	V <sub>I</sub> = V <sub>CC</sub> or GND						
		I <sub>O</sub> = -100 μA; V <sub>CC</sub> = 1.65 V to 5.5 V	V <sub>CC</sub> - 0.1	-	-	V <sub>CC</sub> - 0.1	-	V
		I <sub>O</sub> = -4 mA; V <sub>CC</sub> = 1.65 V	1.2	1.54	-	0.95	-	V
		I <sub>O</sub> = -8 mA; V <sub>CC</sub> = 2.3 V	1.9	2.15	-	1.7	-	V
		I <sub>O</sub> = -12 mA; V <sub>CC</sub> = 2.7 V	2.2	2.50	-	1.9	-	V
		I <sub>O</sub> = -24 mA; V <sub>CC</sub> = 3.0 V	2.3	2.62	-	2.0	-	V
V <sub>OL</sub>	LOW-level output voltage	V <sub>I</sub> = V <sub>CC</sub> or GND						
		I <sub>O</sub> = 100 μA; V <sub>CC</sub> = 1.65 V to 5.5 V	-	-	0.10	-	0.10	V
		I <sub>O</sub> = 4 mA; V <sub>CC</sub> = 1.65 V	-	0.07	0.45	-	0.70	V
		I <sub>O</sub> = 8 mA; V <sub>CC</sub> = 2.3 V	-	0.12	0.30	-	0.45	V
		I <sub>O</sub> = 12 mA; V <sub>CC</sub> = 2.7 V	-	0.17	0.40	-	0.60	V
		I <sub>O</sub> = 24 mA; V <sub>CC</sub> = 3.0 V	-	0.33	0.55	-	0.80	V
I <sub>I</sub>	input leakage current	V <sub>I</sub> = 5.5 V or GND; V <sub>CC</sub> = 0 V to 5.5 V	-	±0.1	±5	-	±100	μA
		V <sub>I</sub> or V <sub>O</sub> = 5.5 V; V <sub>CC</sub> = 0 V	-	±0.1	±10	-	±200	μA
I <sub>CC</sub>	supply current	V <sub>I</sub> = 5.5 V or GND; I <sub>O</sub> = 0 A; V <sub>CC</sub> = 1.65 V to 5.5 V	-	0.1	10	-	200	μA
ΔI <sub>CC</sub>	additional supply current	V <sub>I</sub> = V <sub>CC</sub> - 0.6 V; I <sub>O</sub> = 0 A; V <sub>CC</sub> = 2.3 V to 5.5 V	-	5	500	-	5000	μA
C <sub>I</sub>	input capacitance	V <sub>CC</sub> = 3.3 V; V <sub>I</sub> = GND to V <sub>CC</sub>	-	5.0	-	-	-	pF

[1] All typical values are measured at maximum V<sub>CC</sub> and T<sub>amb</sub> = 25 °C.

**Table 8. Transfer characteristics**

Voltages are referenced to GND (ground = 0 V); for load circuit see [Figure 8](#).

Symbol	Parameter	Conditions	-40 °C to +85 °C			-40 °C to +125 °C		Unit
			Min	Typ <sup>[1]</sup>	Max	Min	Max	
V <sub>T+</sub>	positive-going threshold voltage	see <a href="#">Figure 9</a> and <a href="#">Figure 10</a>						
		V <sub>CC</sub> = 1.8 V	0.82	1.0	1.14	0.79	1.14	V
		V <sub>CC</sub> = 2.3 V	1.03	1.2	1.40	1.00	1.40	V
		V <sub>CC</sub> = 3.0 V	1.29	1.5	1.71	1.26	1.71	V
		V <sub>CC</sub> = 4.5 V	1.84	2.1	2.36	1.81	2.36	V
		V <sub>CC</sub> = 5.5 V	2.19	2.5	2.79	2.16	2.79	V

**Table 8. Transfer characteristics ...continued**

Voltages are referenced to GND (ground = 0 V); for load circuit see [Figure 8](#).

Symbol	Parameter	Conditions	-40 °C to +85 °C			-40 °C to +125 °C		Unit
			Min	Typ <sup>[1]</sup>	Max	Min	Max	
V <sub>T-</sub>	negative-going threshold voltage	see <a href="#">Figure 9</a> and <a href="#">Figure 10</a>						
		V <sub>CC</sub> = 1.8 V	0.46	0.6	0.75	0.46	0.78	V
		V <sub>CC</sub> = 2.3 V	0.65	0.8	0.96	0.65	0.99	V
		V <sub>CC</sub> = 3.0 V	0.88	1.0	1.24	0.88	1.27	V
		V <sub>CC</sub> = 4.5 V	1.32	1.5	1.84	1.32	1.87	V
		V <sub>CC</sub> = 5.5 V	1.58	1.8	2.24	1.58	2.27	V
V <sub>H</sub>	hysteresis voltage	(V <sub>T+</sub> - V <sub>T-</sub> ); see <a href="#">Figure 9</a> , <a href="#">Figure 10</a> and <a href="#">Figure 11</a>						
		V <sub>CC</sub> = 1.8 V	0.26	0.4	0.51	0.19	0.51	V
		V <sub>CC</sub> = 2.3 V	0.28	0.4	0.57	0.22	0.57	V
		V <sub>CC</sub> = 3.0 V	0.31	0.5	0.64	0.25	0.64	V
		V <sub>CC</sub> = 4.5 V	0.40	0.6	0.77	0.34	0.77	V
		V <sub>CC</sub> = 5.5 V	0.47	0.6	0.88	0.41	0.88	V

[1] All typical values are measured at T<sub>amb</sub> = 25 °C

## 12. Dynamic characteristics

**Table 9. Dynamic characteristics**

Voltages are referenced to GND (ground = 0 V); for load circuit see [Figure 8](#).

Symbol	Parameter	Conditions	-40 °C to +85 °C			-40 °C to +125 °C		Unit
			Min	Typ <sup>[1]</sup>	Max	Min	Max	
t <sub>pd</sub>	propagation delay	A to Y; see <a href="#">Figure 7</a> <sup>[2]</sup>						
		V <sub>CC</sub> = 1.65 V to 1.95 V	1.0	4.1	11.0	1.0	14.0	ns
		V <sub>CC</sub> = 2.3 V to 2.7 V	0.7	2.8	6.5	0.7	8.5	ns
		V <sub>CC</sub> = 2.7 V	0.7	3.2	6.5	0.7	8.5	ns
		V <sub>CC</sub> = 3.0 V to 3.6 V	0.7	3.0	5.5	0.7	7.0	ns
		V <sub>CC</sub> = 4.5 V to 5.5 V	0.7	2.2	5.0	0.7	6.5	ns
C <sub>PD</sub>	power dissipation capacitance	V <sub>CC</sub> = 3.3 V; V <sub>I</sub> = GND to V <sub>CC</sub> <sup>[3]</sup>	-	15.4	-	-	-	pF

[1] Typical values are measured at T<sub>amb</sub> = 25 °C and V<sub>CC</sub> = 1.8 V, 2.5 V, 2.7 V, 3.3 V and 5.0 V respectively.

[2] t<sub>pd</sub> is the same as t<sub>PLH</sub> and t<sub>PHL</sub>.

[3] C<sub>PD</sub> is used to determine the dynamic power dissipation (P<sub>D</sub> in μW).

$$P_D = C_{PD} \times V_{CC}^2 \times f_i + (C_L \times V_{CC}^2 \times f_o) \text{ where:}$$

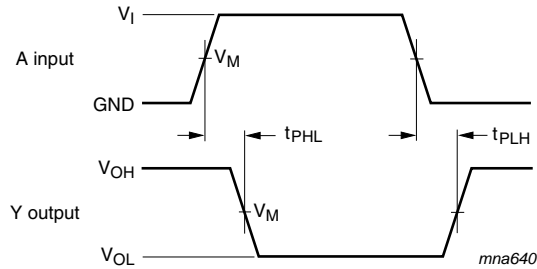
f<sub>i</sub> = input frequency in MHz;

f<sub>o</sub> = output frequency in MHz;

C<sub>L</sub> = output load capacitance in pF;

V<sub>CC</sub> = supply voltage in V.

13. Waveforms

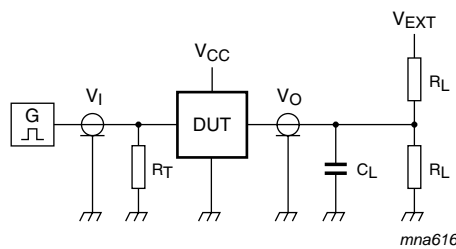


Measurement points are given in [Table 10](#).  
 $V_{OL}$  and  $V_{OH}$  are typical output voltage levels that occur with the output load.

**Fig 7. The data input (A) to output (Y) propagation delays**

**Table 10. Measurement points**

Supply voltage	Input	Output
$V_{CC}$	$V_M$	$V_M$
1.65 V to 1.95 V	$0.5V_{CC}$	$0.5V_{CC}$
2.3 V to 2.7 V	$0.5V_{CC}$	$0.5V_{CC}$
2.7 V	1.5 V	1.5 V
3.0 V to 3.6 V	1.5 V	1.5 V
4.5 V to 5.5 V	$0.5V_{CC}$	$0.5V_{CC}$



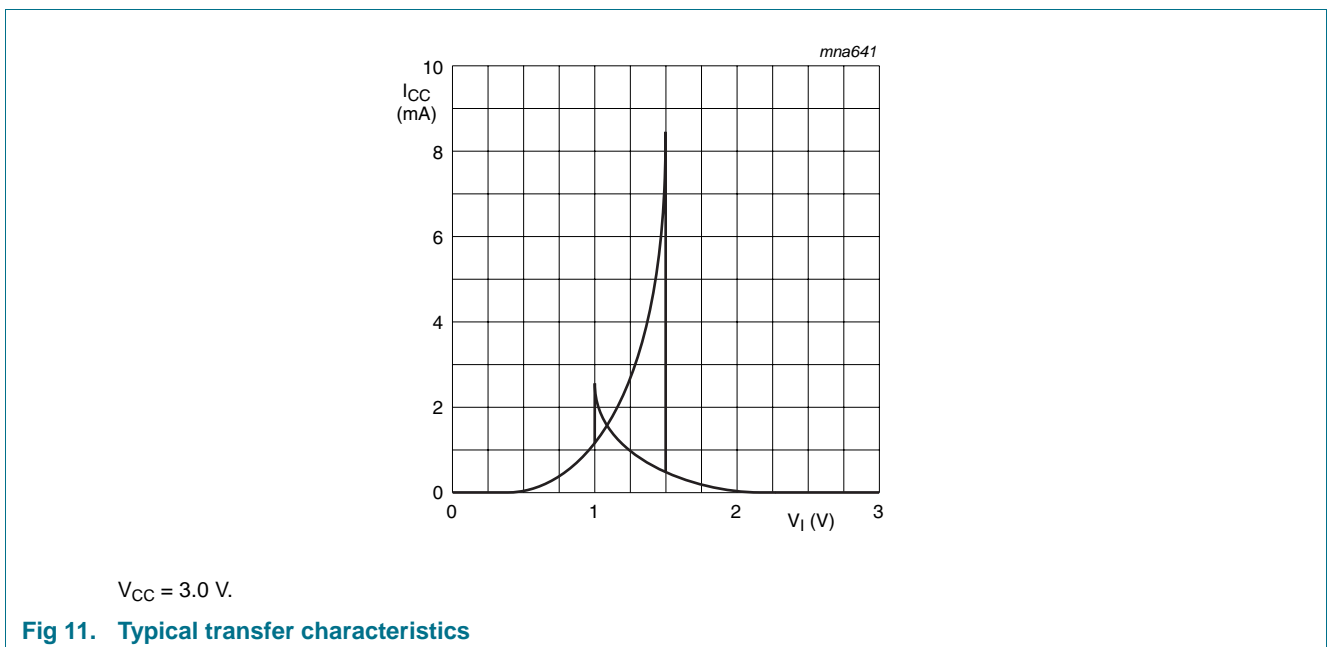
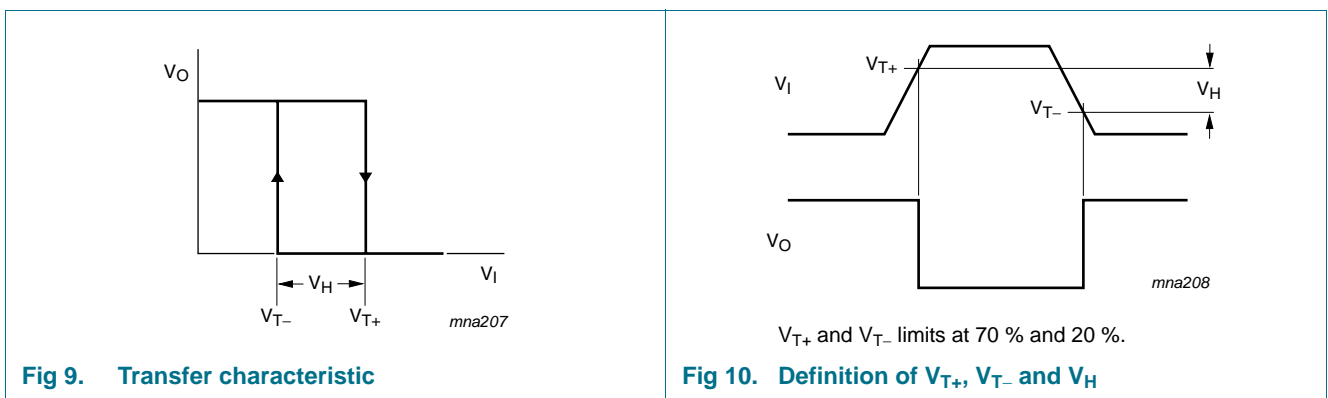
Test data is given in [Table 11](#).  
 Definitions for test circuit:  
 $R_L$  = Load resistance.  
 $C_L$  = Load capacitance including jig and probe capacitance.  
 $R_T$  = Termination resistance should be equal to the output impedance  $Z_o$  of the pulse generator.  
 $V_{EXT}$  = External voltage for measuring switching times.

**Fig 8. Test circuit for measuring switching times**

Table 11. Test data

Supply voltage	Input		Load		V <sub>EXT</sub>
V <sub>CC</sub>	V <sub>I</sub>	t <sub>r</sub> = t <sub>f</sub>	C <sub>L</sub>	R <sub>L</sub>	t <sub>PLH</sub> , t <sub>PHL</sub>
1.65 V to 1.95 V	V <sub>CC</sub>	≤ 2.0 ns	30 pF	1 kΩ	open
2.3 V to 2.7 V	V <sub>CC</sub>	≤ 2.0 ns	30 pF	500 Ω	open
2.7 V	2.7 V	≤ 2.5 ns	50 pF	500 Ω	open
3.0 V to 3.6 V	2.7 V	≤ 2.5 ns	50 pF	500 Ω	open
4.5 V to 5.5 V	V <sub>CC</sub>	≤ 2.5 ns	50 pF	500 Ω	open

### 14. Waveforms transfer characteristics





### 15. Application information

The slow input rise and fall times cause additional power dissipation, this can be calculated using the following formula:

$$P_{add} = f_i \times (t_r \times \Delta I_{CC(AV)} + t_f \times \Delta I_{CC(AV)}) \times V_{CC} \text{ where:}$$

$P_{add}$  = additional power dissipation ( $\mu\text{W}$ );

$f_i$  = input frequency (MHz);

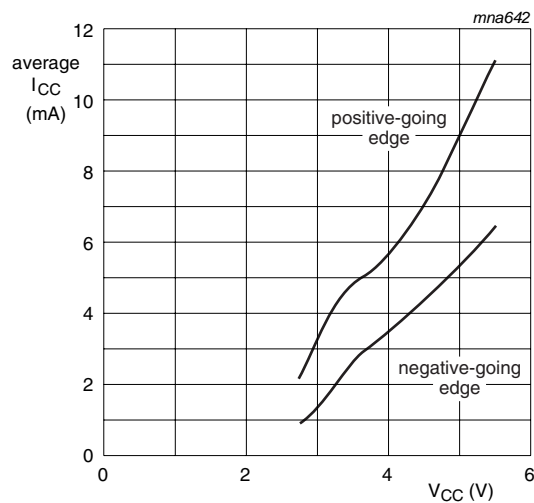
$t_r$  = input rise time (ns); 10 % to 90 %;

$t_f$  = input fall time (ns); 90 % to 10 %;

$\Delta I_{CC(AV)}$  = average additional supply current ( $\mu\text{A}$ ).

Average  $\Delta I_{CC(AV)}$  differs with positive or negative input transitions, as shown in [Figure 12](#).

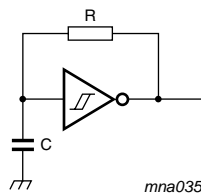
An example of a relaxation circuit using the 74LVC1G14 is shown in [Figure 13](#).



Linear change of  $V_i$  between 0.8 V to 2.0 V.

All values given are typical unless otherwise specified.

**Fig 12. Average additional supply current as a function of supply voltage**



$$f = \frac{1}{T} \approx \frac{1}{0.5 \times RC}$$

**Fig 13. Relaxation oscillator**

16. Package outline

TSSOP5: plastic thin shrink small outline package; 5 leads; body width 1.25 mm

SOT353-1

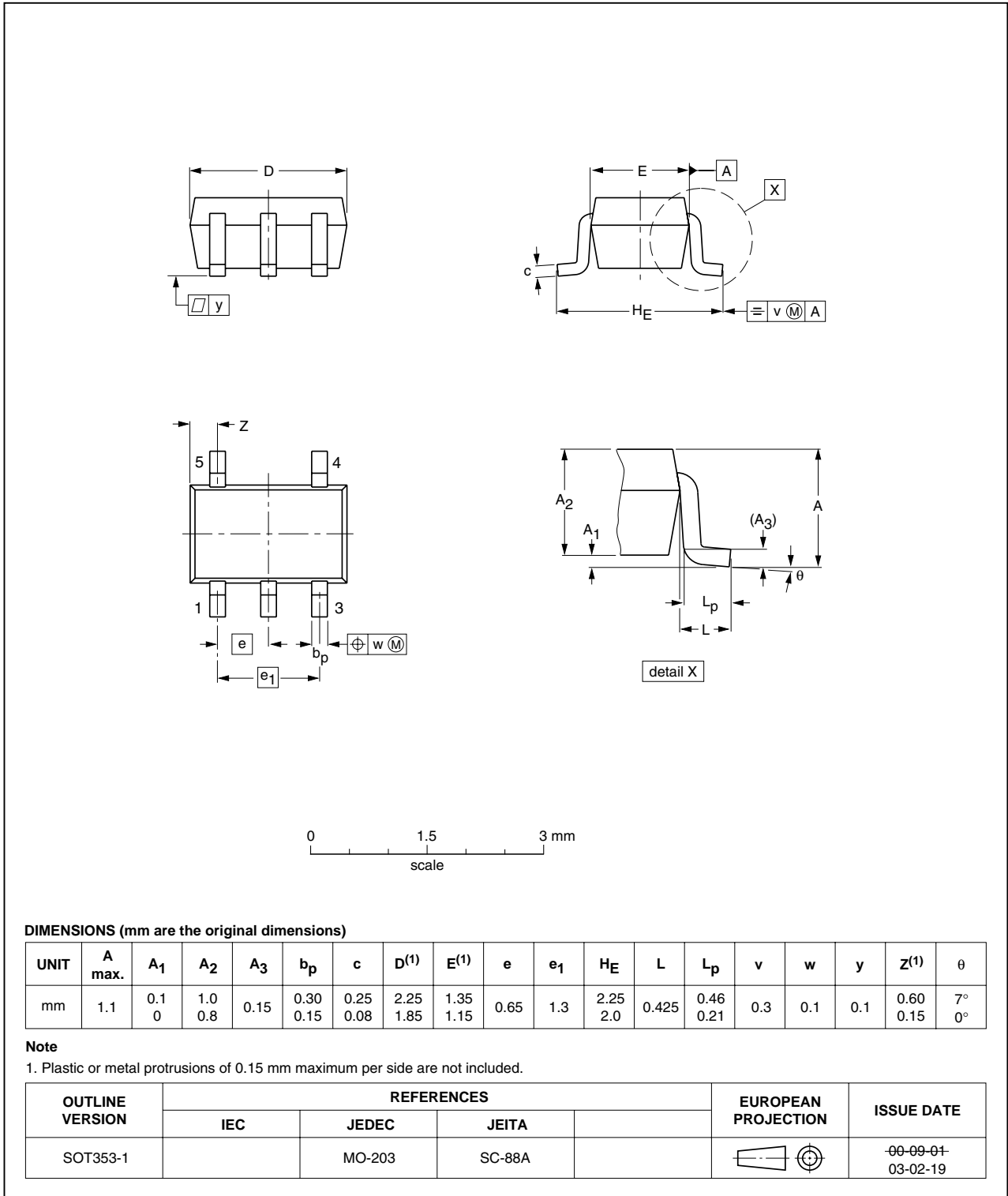


Fig 14. Package outline SOT353-1 (TSSOP5)

Plastic surface-mounted package; 5 leads

SOT753

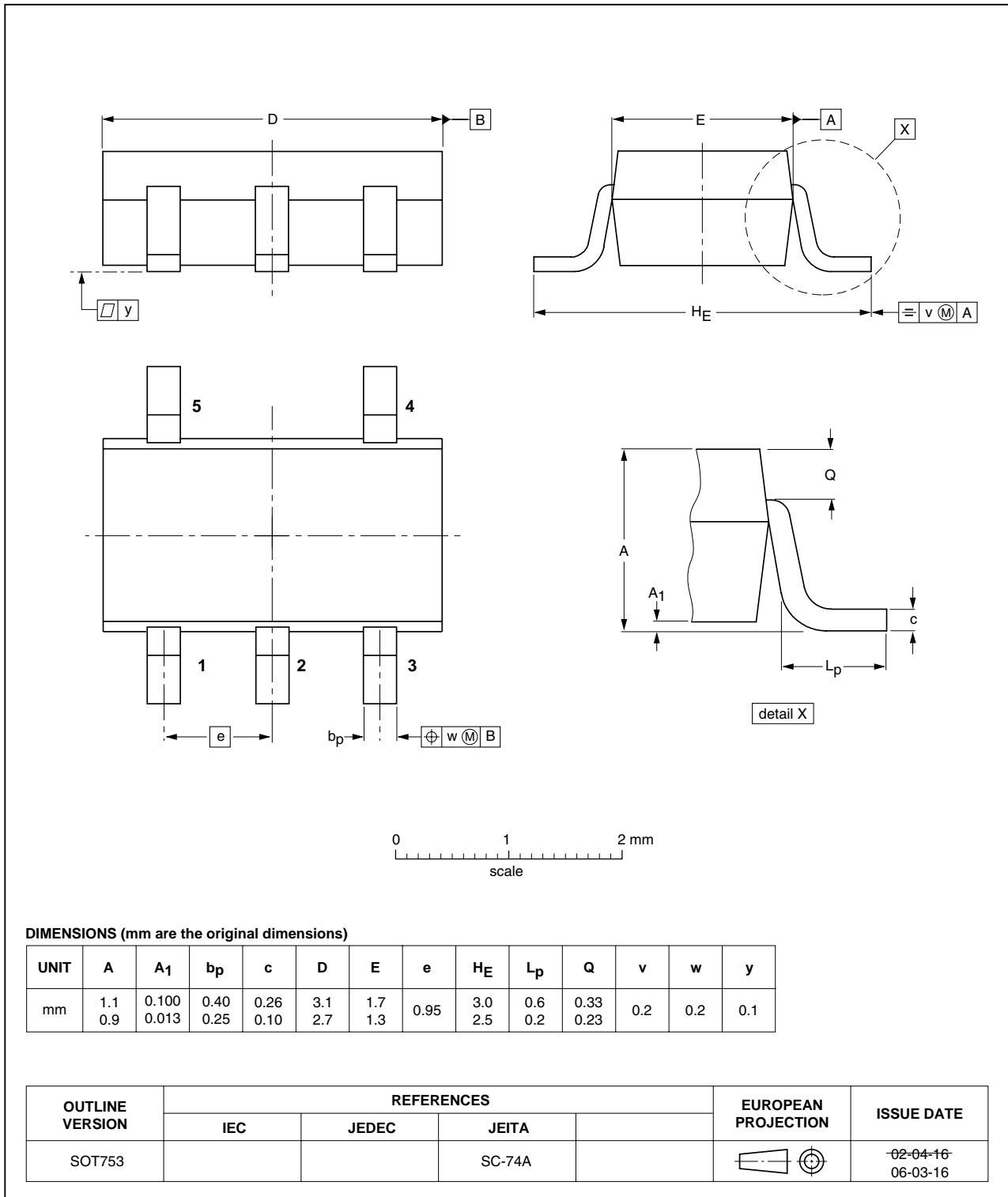


Fig 15. Package outline SOT753 (SC-74A)

XSON6: plastic extremely thin small outline package; no leads; 6 terminals; body 1 x 1.45 x 0.5 mm

SOT886

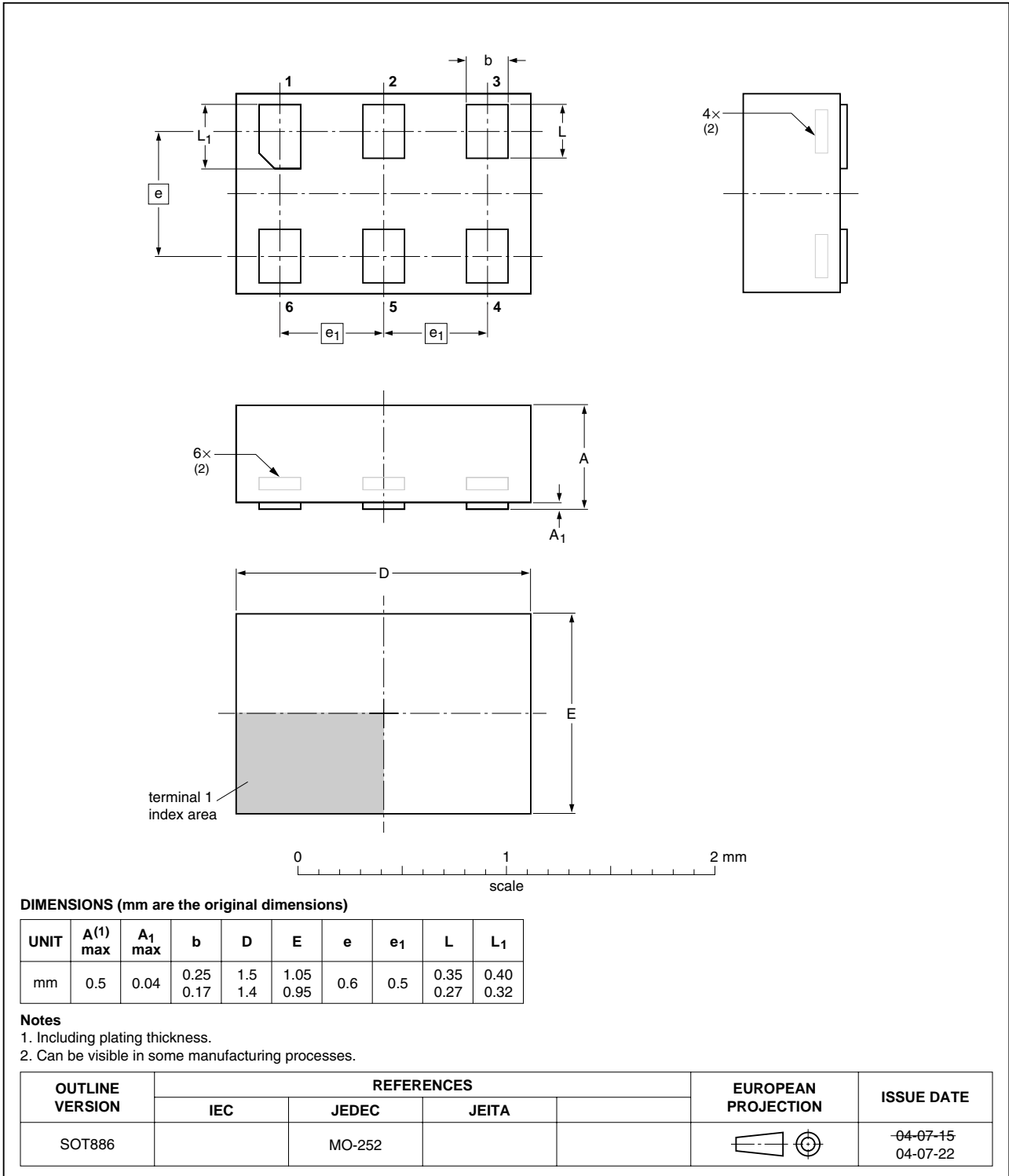


Fig 16. Package outline SOT886 (XSON6)

XSON6: plastic extremely thin small outline package; no leads; 6 terminals; body 1 x 1 x 0.5 mm

SOT891

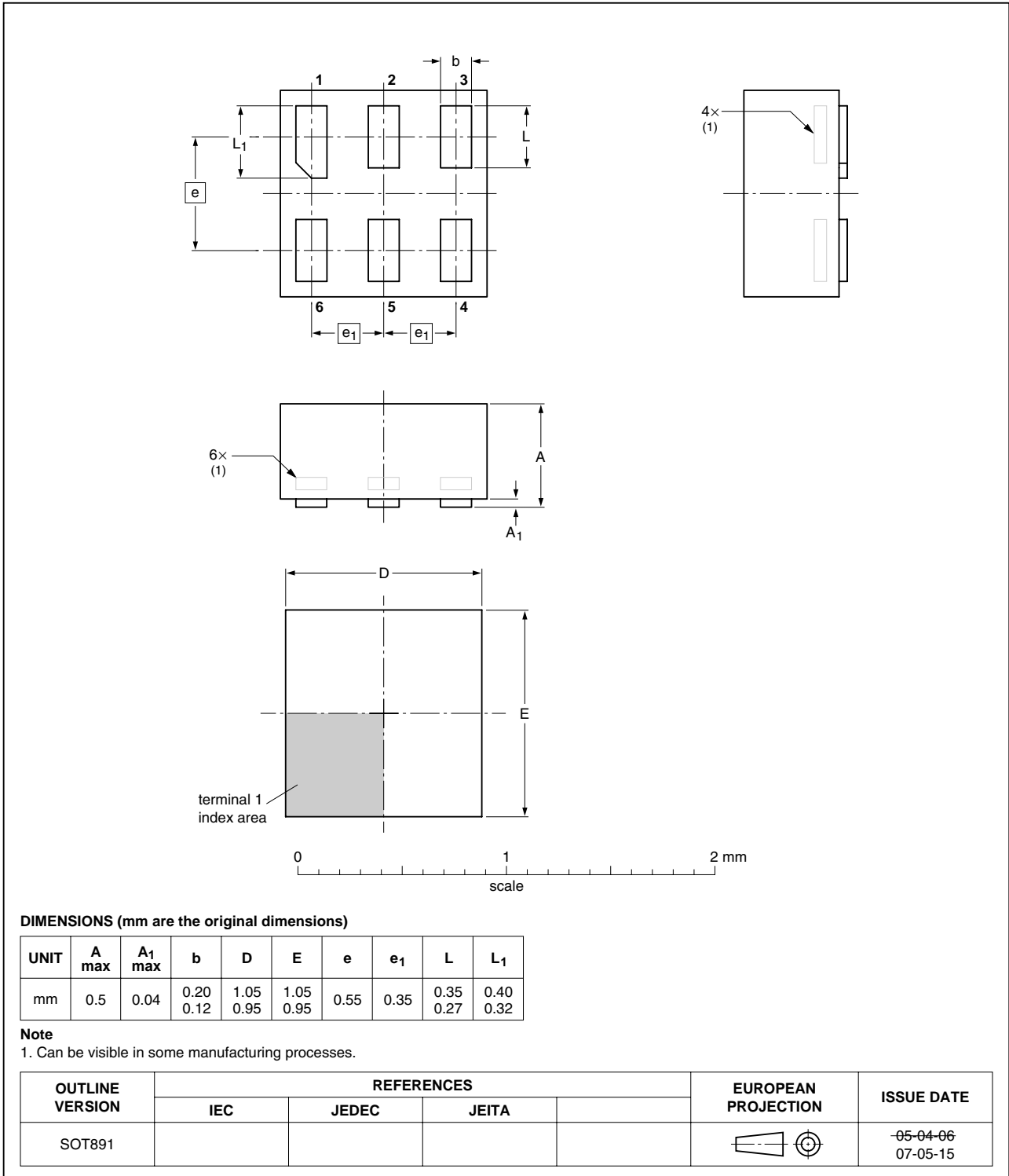


Fig 17. Package outline SOT891 (XSON6)

**XSON6: extremely thin small outline package; no leads;  
6 terminals; body 0.9 x 1.0 x 0.35 mm**

SOT1115

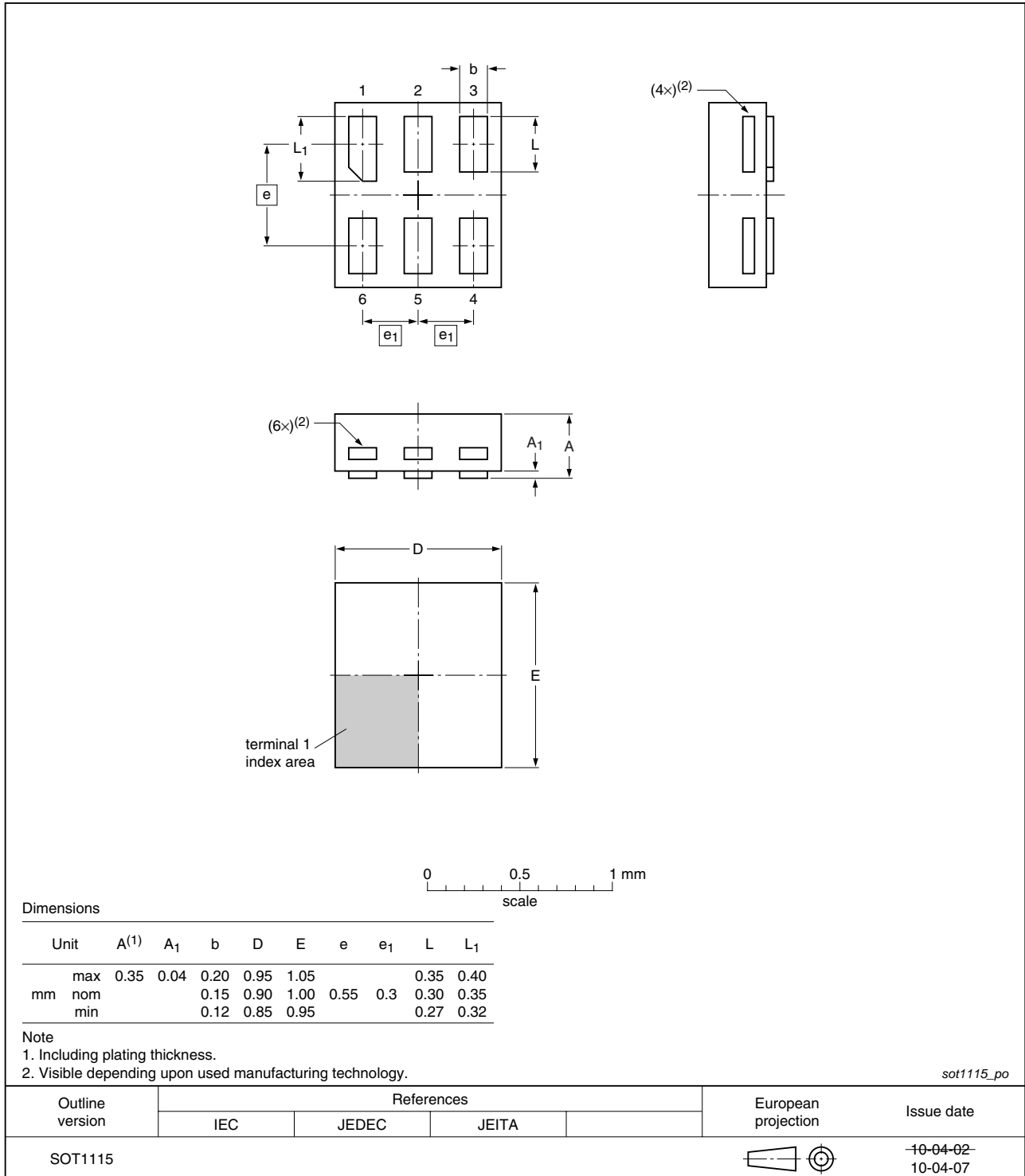


Fig 18. Package outline SOT1115 (XSON6)

**XSON6: extremely thin small outline package; no leads;  
6 terminals; body 1.0 x 1.0 x 0.35 mm**

SOT1202

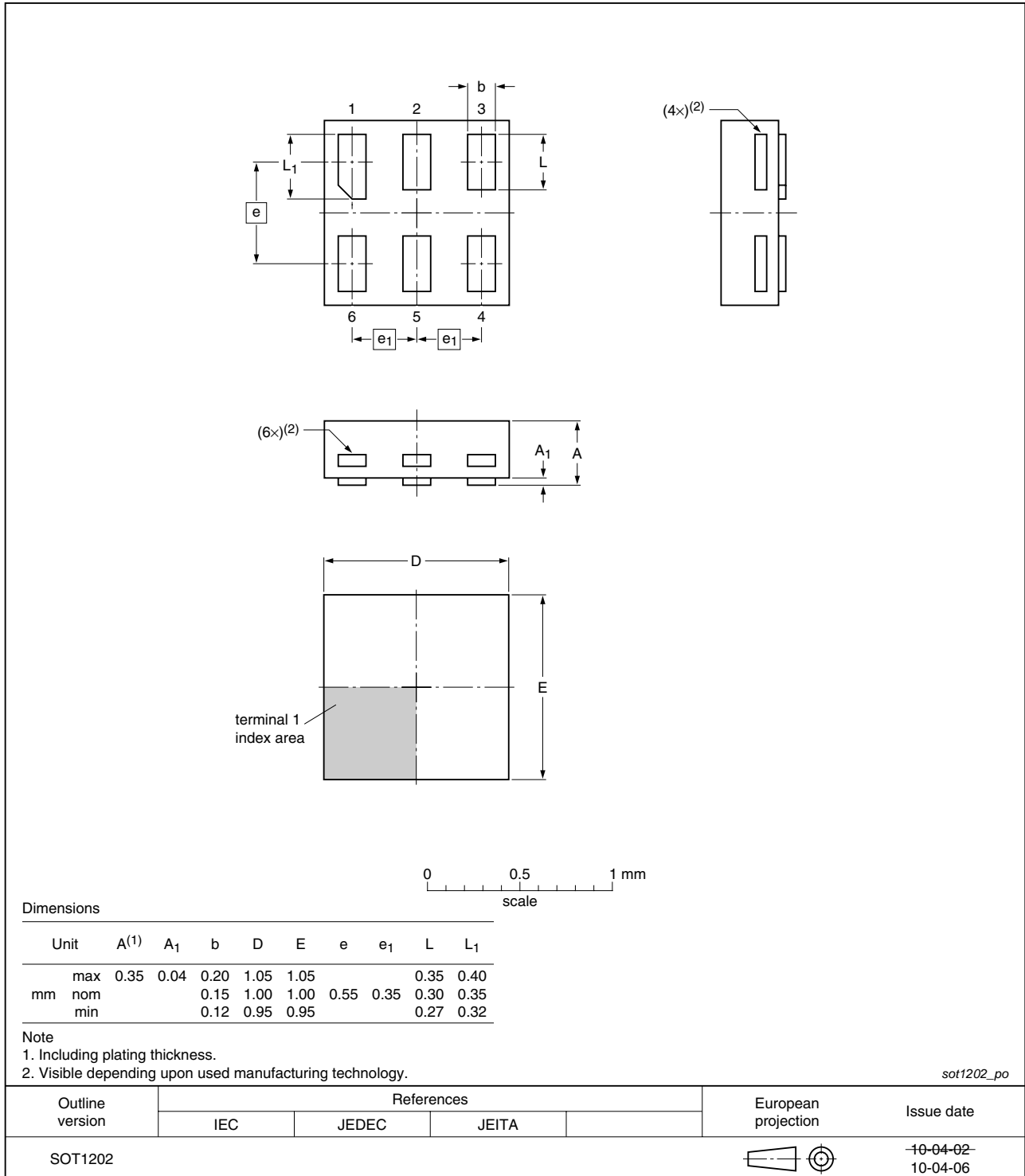


Fig 19. Package outline SOT1202 (XSON6)

## 17. Abbreviations

Table 12. Abbreviations

Acronym	Description
CMOS	Complementary Metal Oxide Semiconductor
TTL	Transistor-Transistor Logic
HBM	Human Body Model
ESD	ElectroStatic Discharge
MM	Machine Model
DUT	Device Under Test

## 18. Revision history

Table 13. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74LVC1G14 v.8	20101110	Product data sheet	-	74LVC1G14 v.7
Modifications:	<ul style="list-style-type: none"> <li>Added type number 74LVC1G14GN (SOT1115 / XSON6 package).</li> <li>Added type number 74LVC1G14GS (SOT1202 / XSON6 package).</li> </ul>			
74LVC1G14 v.7	20070718	Product data sheet	-	74LVC1G14 v.6
74LVC1G14 v.6	20060615	Product data sheet	-	74LVC1G14 v.5
74LVC1G14 v.5	20040910	Product specification	-	74LVC1G14 v.4
74LVC1G14 v.4	20021119	Product specification	-	74LVC1G14 v.3
74LVC1G14 v.3	20020521	Product specification	-	74LVC1G14 v.2
74LVC1G14 v.2	20010406	Product specification	-	74LVC1G14 v.1
74LVC1G14 v.1	20001212	Product specification	-	-



## 19. Legal information

### 19.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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